

# Inline Selective-3D Automatic Optical Inspection System

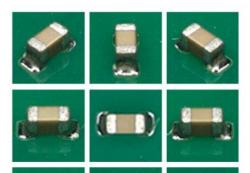
	Revolutionary Selective 3D imaging technology	Selective 3D imaging, Side cameras integrated in 3D processing.
$\checkmark$	Newest generation 5MP USB 3 Vision Cameras	The latest generation of high speed, high quality cameras No capture card requirements.
	2X FOV over previous Generation	Up to 50% reduction of cycle time.
$\checkmark$	Multi-color 4 angle lighting with Line Source Coaxial Lighting and Meniscus Profiler	Reliable solder joint meniscus and pad surface analysis to find solder and paste printing defects
$\sqrt{}$	Inspects:	Can be used for inspection in all stages of the production process; in-process inspection, final inspection, and first article.
$\checkmark$	Flexible classification and reporting scenarios	Integrate AOI efficiently in your existing operations and factory layout
$\checkmark$	Line Sourced DOAL (Direct On Axis Lighting) coaxial lighting system with high resolution Telecentric Optics	Inspect solder joints without shadow effects from tall components nearby and accurate inspection model building
	Low Noise Large CCD High Speed 24 bit Color Camera	Find defects easier including printing defects on Gold or Copper plated PCB's
	Synthetic Imaging and Spectral Analysis	Powerful algorithms to achieve an optimal balance between defect detection and false call levels in shortest time
	Triple-use of side cameras	Use in automatic inspection program and defect classification + repair post-inspection
	Prototype mode for 1st off inspection	Program in minutes to verify your production line is setup correctly before starting full production

 $\sqrt{\phantom{a}}$  In height adjustable optical head

Compensate for PCB warp and adapt to tall component and sandwich assemblies

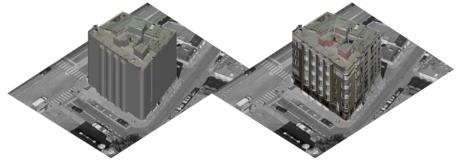


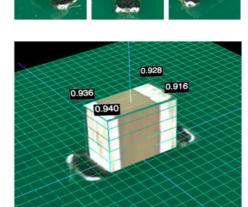
## Hardware and Software Features



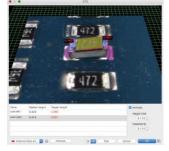
### Revolutionary 3D imaging

True Stereoscopic imaging using 9 cameras. Full colour 3D allows the ability to actually see the side of components rather than extruded 2D images. Using the addition of a 4th LED white light









## The Perfect Combination of 3D and 2D Inspection Algorithms

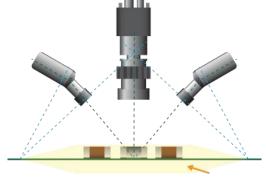
Height, tilt and coplanarity measurement. Pin Height measurement Component Presence Absence, Polarity, Value, Angle, Offset, Colour, Extra part detection, Solder ball detection, Solder profile analysis and short detection. The thickness of chip capacitors in combination with colour makes a more reliable inspection when checking chip capacitors value.

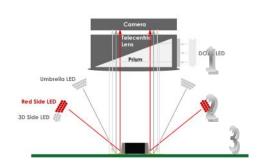
## Unique 3D Stereoscopic Vision

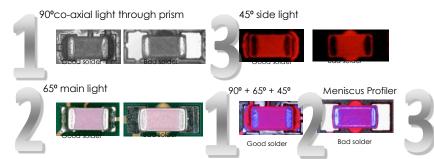
Utilizing the full 9 cameras of the MEK camera head. The image differential are merged and a vectorised map of the component is created. Then analyzed based on the programmers applied tolerances. The vectorised map of the components removes the minor imperfection of the component surface giving more accurate measurement of height and surface angle of the component with reduced chance of false readings.

## Omnidirectional Multi-Angle, Multi-Color LED lighting

Optimal light no matter component direction — 3D color profile of solder meniscus — Reliable defect decision by the software — Decide Good Solder, No Solder, Lack of Solder and Too much solder for SMT and THT solder joints







## 8x Angular Side Sensors (Only available for JTAz and JDAz models)

Simultaneously operating, multiplexed side view sensors with USB Vision interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database



## Hardware and Software Features — Continued

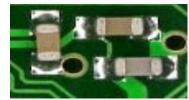
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## Double size FOV (Field of view)

Up to 2x faster inspection over previous generations of machines. Square FOV combined with circular lighting allows for program rotation without time consuming debugging.

## Large pixel image capturing sensor

15µm² pixel size — less noise — smooth and detailed image— great dynamic range





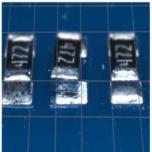
High dynamics sensor

Conventional sensor

## In Height Adjustable Optical Head

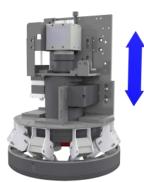
In Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness - PCB Warp Compensation — Inspection of PCB's with very tall components — Reliable text and/or polarity inspection on tall components

Inspection of "Sandwich" assemblies without need of jigs and multiple inspections



**Shift & Tilt Side View lenses** 

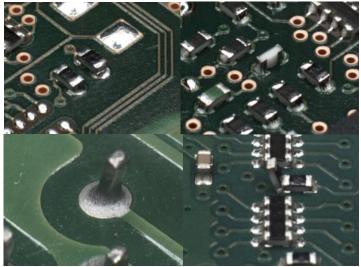
Distortion-free side images across whole FoV. Every point on the PCB within the FoV has same distance to the capturing sensor despite the angle of the optics





With Shift&Tilt Lens







# **Inline**

# Enwerspectar

## JTAz/JDAz

350L, 650L, 800L

In-Line Series Specifications	PowerSpector JTAz 350L	PowerSpector JTAz 650L	PowerSpector JTAz 800L	
m-time series specifications	350x250mm (13.8"x9.8")	650x550mm (25.6"x21.6")	800x550mm (31.5"x21.6")	
Maximum PCB Size	·	is slightly smaller due to larg		
Characteristic		is slightly strictler ace to larg	ger diameter optical offic	
Product type		Automatic Optical Inspecto	or .	
In-line/Off-line	,			
Camera movement		In-Line X + Y Direction		
PCB movement				
Parts inspection	Stationary during inspection			
	Presence, Polarity, Offset, Correctness, Soldering, Height			
Printing/paste inspection	Offset, Smearing, Bridges, Uniformity			
Image Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits			
Image Parameters	Brightness, Hue, Saturation via Filters			
Camera type	4.8 MP CCD Digital with USB 3 Vision			
Camera Field Of View/Resolution	36 x 30mm(1.42" x 1.18")/15.0 µm			
Lens	Telecentric lens with built in prism for DOAL Lighting			
l	Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced			
Lighting system	DOAL (Diffused On Axis Lighting (Coaxial))			
Specification		2511 (0 4 0 0 ) (10 )	P \	
Minimum inspection component size	01005" (0.4x0.2mm) (10µm resolution)			
Positioning accuracy		Pixel related Feedback Loop		
Component clearance (top)	JTAz 30mm (1.2")/ JDAz 60mm (2.4")			
Side Cameras	8x Digital color USB 3.0 Vision in 45/45 orientation			
Z-Axis movement range	30mm (1.2")			
Component clearance (bottom)	35mm (1.38") or 55mm (2.17") without PCB support lift option			
Movement speed	720mm/s			
Inspection capacity typical		2750ppm		
Electrical requirements	100-240 VAC / 330W			
Conveyo	r			
Conveyor belt speed	10-500mm/s (0.4-19.7"/s)			
Conveyor configuration	Left>RigI	Left>Right, Front rail fixed, Height 830-950mm		
PCB Clamping	Top Justified, Ruler Blade, Top & Edge Clamping, Sensor Stopper			
Minimum board size	50x50mm (2.0" x 2.0")			
Board thickness	0.6-2mm (option 0.6-4mm) (24mils - 79mils)			
PCB warpage compensation	Automatic PCB support Lift with magnetic pins (option)			
Interfacing				
Control PC type	Apple Mac Mini or iMac			
Control interface	SMEMA (conveyer)			
Data interface	USB and Thunderbolt			
Programming Interface	CSV Centroid file (Placem		file)	
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)			
3rd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)			
Genero	ıl			
Operating temperature	15-30 deg. C(60-90 deg. F)			
Operating humidity	15-80 % RH			
	W740 x D786 x H1236	W1040 x D1077 x H1270	W1190 x D1077 x H1259	
External size	(29.1" x 30.9" x 48.7")	(40.9" x 42.4" x 50.0")	(46.9" x 42.4" x 49.5")	
Weight	180kg (397lbs)	240kg (529lbs)	290kg (639lbs)	

Mek Europe reserves the right to change the design and specifications without notice. @ Mek Europe BV, October 2022 R3

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